What is claimed is:

1. A system adapted to analyze a semiconductor die, the system comprising:

a light source;

a semiconductor analysis arrangement adapted to hold a semiconductor die and to use light from the light source to perturb the die for analyzing the die; and

a fiber optic cable coupled between the light source and the analysis arrangement and adapted to direct light from the light source to the die in the analysis arrangement.

2. The system of claim 1, further comprising a light direction arrangement adapted to direct light from the fiber optic cable to a selected portion of the die.

3. The system of claim 1, wherein the light source includes a laser source.

4. The system of claim 1, wherein the semiconductor analysis arrangement includes a test chamber having a fixture adapted to hold the semiconductor die.

5. The system of claim 4, wherein the analysis arrangement is adapted to evacuate the test chamber.

6. The system of claim 5, wherein the light source is located outside of the test chamber, and wherein the fiber optic cable extends from the light source and into the test chamber.

7. The system of claim 1, further comprising a controller adapted to control the semiconductor analysis arrangement.

8. The system of claim 7, wherein the controller includes a computer.

9. The system of claim 1, wherein the fiber optic cable includes a primary fiber optic waveguide surrounded by a protective fiber optic waveguide.

10. The system of claim 1, wherein the fiber optic cable extends into the analysis arrangement and is adapted to direct light to a semiconductor die held in the analysis arrangement.

11. The system of claim 1, wherein the analysis arrangement includes a detection arrangement adapted to detect a response from the die to the light.

12. The system of claim 11, wherein the detection arrangement is adapted to detect a failure condition of the die.

13. The system of claim 1, further comprising at least one perturbation device in addition to the light source, the perturbation device adapted to perturb the die.

14. A system adapted to analyze a semiconductor die, the system comprising:

means for generating light;

means for holding a semiconductor die and using the generated light to perturb the die for analyzing the die; and

a fiber optic cable coupled between the means for generating light and the means for holding a semiconductor die and adapted to direct light from the means for generating light to the means for holding a semiconductor die.

15. A method for analyzing a semiconductor die, the method comprising:

generating light;

directing the generated light to a die analysis arrangement via a fiber optic cable; and

holding a semiconductor die and using the generated light to perturb the die for analyzing the die.

16. The method of claim 15, wherein generating light includes generating laser light.

17. The method of claim 15, wherein using the generated light for analyzing the die includes directing the generated light to a selected portion of the die and stimulating the selected portion, further comprising detecting a response from the die to the stimulation and using the response to detect a characteristic of the die.

18. The method of claim 17, wherein using the response to detect a characteristic of the die includes detecting a cause of a failure of the die.

19. The method of claim 15, further comprising placing the die in a vacuum chamber and drawing a vacuum on the chamber, wherein holding the die includes holding the die in the chamber, wherein generating light includes generating light outside of the vacuum chamber and wherein directing the generated light to a die analysis arrangement via a fiber optic cable includes directing the generated light via a fiber optic cable extending into the vacuum chamber.